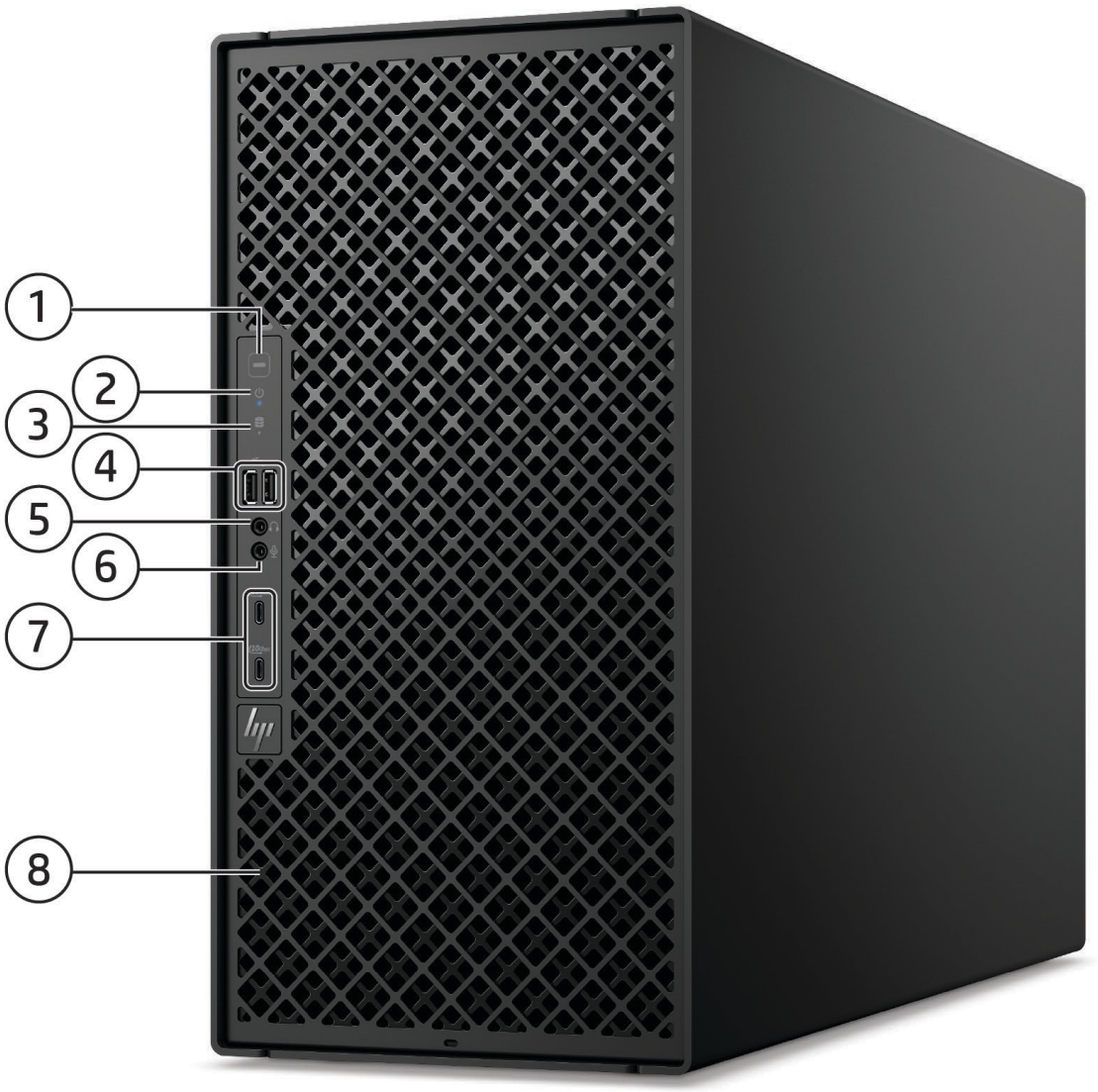
Overview

HP ZGX Fury G1n AI Station

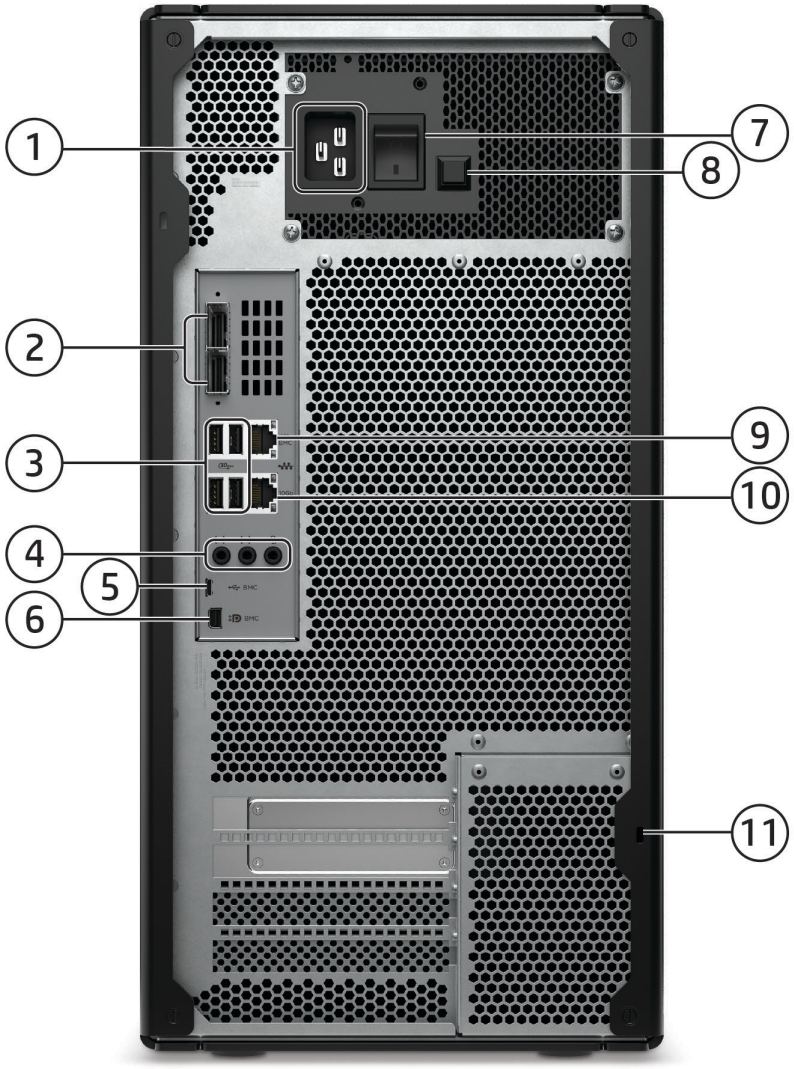


Front

1. Power Button
2. Power LED (Blue)
3. Activity LED (White)
4. 2x USB 3.2 Gen 2.1 (5Gbps) Type-A ports
5. Headphone-Out
6. Microphone-In
7. 2x USB 3.2 Gen 2 (10 Gbps) Type-C ports
8. Dust Filter

Overview

HP ZGX Fury G1n AI Station



Rear

1. 20 AC Inlet
2. 2x QSFP112 (400Gbps) ports
3. 4x USB 3.2 Gen 2 (10 Gbps) ports
4. Line-out, Line-in, Universal audio jack ports
5. Micro-USB to BMC
6. Mini-DP to BMC
7. Power Switch
8. Hybrid Mode button
9. RJ-45 (1 Gbps) to BMC
10. RJ-45 (10 Gbps)
11. Kensington Lock Slot

Features

FORM FACTOR

Liquid Cooled Rackable Tower

OPERATING SYSTEMS

Preinstalled: Ubuntu® 24.04 LTS with NVIDIA AI Developer Tools

Technical Overview

- Product Category
  - Workstation
- Manufacturer
  - HP Inc.
- Manufacturer Address
  - 1501 Page Mill Road, Palo Alto, CA 94304
- Model Number
  - FCLSA-2603
- Year of Manufacture
  - 2026
- Power Supply Efficiency
  - 80 Plus Titanium

1. A certified preloaded version of Ubuntu® 24.04 LTS with NVIDIA AI Developer Tools is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. The update setting is user controllable. ISP fees may apply, and additional requirements may apply over time for upgrades.
NOTE: This product does not support Windows. A full list of HP products and the Windows versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282.

TECHNICAL OVERVIEW

Product Category	Workstation
Manufacturer	HP Inc.
Manufacturer Address	1501 Page Mill Road, Palo Alto, CA 94304
Model Number	FCLSA-2603
Year of Manufacture	2026
Power Supply Efficiency	80 Plus Titanium

Features

PROCESSOR OVERVIEW

Architecture	Grace Blackwell
SoC Model	GB300
GPU Architecture	NVIDIA Blackwell
Tensor Cores	5th Generation
CPU Architecture	ARMv9
CPU Cores	72 cores
CPU Details	NVIDIA Grace 72-Core Neoverse V2
GPU Memory	252 GB HBM3e | 7.1 TB/s
CPU Memory	496 GB LPDDR5X | 396 GB/s

Color	Black
Convertibility	No
Expansion Slots (see system board section for more details)	▪ One PCIe Gen5 x16 slot supporting an optional add-in display GPU ▪ Two PCIe Gen5 x8 expansion slots
Front I/O	2x USB 3.2 Gen2, Type-A, 5Gb ports, 2x USB 3.2 Gen2, Type-C, 10Gb ports, and a combined audio jack supporting mic-in and headphone-out
Internal I/O	4 NVMe connectors for M.2 Storage Devices
Rear I/O	4x USB 3.2 Gen1, Type-A, 10Gb ports, 2x QSFP112, 400Gb Ethernet ports, 1x RJ-45, 10Gb Ethernet, 1x RJ-45, 1Gb Ethernet to BMC for management, 1x Mini DisplayPort to BMC for management, 1x Micro-USB to BMC UART, 1x Audio-in, 1x Line-out, 1x Microphone
Chassis Dimensions (HxWxD)	H: 17.56 [446.0 mm] W: 8.72" [221.5 mm] D: 26.26" [667 mm]
Packaged Dimensions	H: 17.125" [435 mm] W: 23.19" [589 mm] D: 31.75" [806.5 mm]
Rack Dimensions	5U
Power Supply	Titanium Rated 94% Efficient Single 1600W, Power Supply with C20 AC Inlet including additional power adapter for optional graphics cards.
Memory	Four LPDDR5X SOCAMM modules, up to 496 GB

Supported Components

PCIe SOLID STATE DRIVES

	Factory Configured	Option Kit	Option Kit Part Number
2TB M.2 2280 PCB01 PCIe Gen5x4 TLC	Y	N	
2TB M.2 2280 AED1 PCIe Gen5x4 TLC	Y	N	
2TB M.2 2280 PM9E1 PCIe Gen5x4 TLC	Y	N	
2TB M.2 2280 AED1 PCIe Gen5x4 TLC SED	Y	N	
4TB M.2 2280 PM9E1 PCIe Gen5x4 TLC	Y	N	

GRAPHICS

	Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
NVIDIA RTX PRO 2000 Blackwell 16GB	Y	Y	B5CH7AA	
NVIDIA RTX PRO 4000 Blackwell SFF 24GB	Y			
NVIDIA RTX PRO 6000 Blackwell Max-Q 96GB (300W)*	N	Y	B11E9AA	
NVIDIA RTX PRO 6000 Blackwell Workstation Edition 96GB (600W)*	N	Y	B11F0AA	
BMC Management Board	Y	N		

NOTE: Use of an NVIDIA RTX PRO 6000-Max-Q Blackwell Workstation or NVIDIA RTX PRO 6000-Blackwell Workstation card may cause the system to apply a power limit to the GB300 at boot and may impact system performance.

RACKING AND PHYSICAL SECURITY

	Factory Configured	Option Kit	Option Kit Part Number
HP ZGX Fury G1n Rail Rack Kit	Y	N	

SOFTWARE

	Factory Configured	Option Kit
HP ZGX Toolkit	Y	N
HP HP Z Runtime (ZRT) CLI	Y	N
Ubuntu 24.04 LTS with NVIDIA AI Developer Tools	Y	N

SOFTWARE COMPONENTS AND APPLICATIONS

Manageability Software and Features

HP Z Runtime; NVIDIA AI Developer Tools;

BIOS

NVIDIA approved partner-developed BIOS

Security Software and Management

NVIDIA approved partner-developed BMC Firmware

Trusted Platform Module (TPM) 2.0; UEFI version 2.9

UEFI Secure Boot

Technical Specifications – System Board

SYSTEM BOARD

System Board Form Factor	H: 12.0" [304.8mm] W: 11.21" [284.84mm]
Processor Socket	n/a (CPU is soldered down)
Memory Expansion Slots	4x 128GB SOCAMM modules up to 496 GB total system memory
Memory Type Supported	LPDDR5X ECC
Memory Speed Supported	396GB/s for CPU Memory. 7.1 TB/s for GPU Memory
Maximum Memory	748GB
Memory Configuration (Supported)	4 x 128GB SOCAMM Modules.
PCI Express Connectors	▪ One PCIe Gen5 x16 slot supporting an optional add-in display GPU ▪ Two PCIe Gen5 x8 expansion slots ▪ 4 M.2 Slots (2x M2 PCIe Gen6 x4 and 2x M2 PCIe Gen5 x4)

Technical Specifications – System Board

USB Connector(s)	**Front**	Front I/O: 2x USB 3.1 2 Gen2, Type-A, 5Gb ports, 2x USB 3.1 2 Gen2, Type-C, 10Gb ports, Combined audio jack supporting mic-in and headphone-out
	Rear	4x USB 3.2 Gen1, Type-A, 10Gb ports, 2x QSFP112, 400Gb Ethernet ports, 1x RJ-45, 10Gb Ethernet, 1x RJ-45, 1Gb Ethernet to BMC for management, 1x Mini DisplayPort to BMC for management, 1x Micro-USB to BMC UART, 1x Audio-in, 1x Line-out, 1x Microphone
Power Supply		Titanium Rated 94% Efficient Single 1600W, Power Supply with C20 AC Inlet including additional power adapter for optional graphics cards.

Technical Specifications – System Configurations

SYSTEM CONFIGURATIONS

ZGX Fury G1n Configuration #1	
Processor Info	Nvidia GB300 HPM with Nvidia Grace 72-core NeoVerse V2
Memory Info	496GB (4x128GB) LPDDR5X SOCAMM ECC Memory
Graphics Info	1x NVIDIA Blackwell Ultra GB300 GPU, 252GB HBM3e GPU Memory, 1x NVIDIA RTX PRO 2000 Blackwell (75W) card
Disks/Optical/Floppy	4x 2TB PCIe Gen5 M.2 SSD
PSU	Titanium Rated, 94% Efficient 1600W Power Supply
Other	NA

Energy Consumption (Watts)						
	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	TBD		TBD		TBD	
Windows short Idle (S0)	TBD		TBD		TBD	
Windows Busy Typ (S0)	TBD		TBD		TBD	
Windows Busy Max (S0)	TBD		TBD		TBD	
Sleep (S3)	TBD	TBD	TBD	TBD	TBD	TBD
Off (S5)	TBD	TBD	TBD	TBD	TBD	TBD
Zero Power Mode (EuP)	TBD		TBD		TBD	

ZGX Fury G1n Configuration #2	
Processor Info	Nvidia GB300 HPM with Nvidia Grace 72-core NeoVerse V2
Memory Info	496GB (4x128GB) LPDDR5X SOCAMM ECC Memory
Graphics Info	1x NVIDIA Blackwell Ultra GB300 GPU, 252GB HBM3e GPU Memory, 1x NVIDIA RTX PRO 4000 SFF Blackwell (75W)
Disks/Optical/Floppy	2x 2TB PCIe Gen5 M.2 SSD, 2x 4TB PCIe Gen5 M.2 SSD
PSU	Titanium Rated, 94% Efficient 1600W Power Supply
Other	NA

Technical Specifications – System Configurations

GX Fury G1n Configuration #3	
Processor Info	Nvidia GB300 HPM with Nvidia Grace 72-core NeoVerse V2
Memory Info	496GB (4x128GB) LPDDR5X SOCAMM ECC Memory
Graphics Info	1x NVIDIA Blackwell Ultra GB300 GPU, 252GB HBM3e GPU Memory
Disks/Optical/Floppy	4x 2TB PCIe Gen5 M.2 Self-encrypting SSD NMIC
PSU	Titanium Rated, 94% Efficient 1600W Power Supply
Other	NA

Technical Specifications – Power

POWER SUPPLY

Operating Voltage Range	90-264VAC
Rated Voltage Range	100-240VAC
Rated Line Frequency	50-60 Hz
Frequency Range	47-63Hz
Built-in Self Test (BIST) **LED**	Yes
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	Yes

ENERGY DATA

Test Parameters	230 Vac/50Hz
Maximum Power (Watts)	1618 W
Idle Power (Watts)	308 W
Sleep Mode Power (Watts)	N/A (No sleep power mode)
Off Mode Power (Watts)	5.25 W
Internal Power Supply Efficiency	a) 95.27 % efficiency at 50% rated output power b) 94.78 % efficiency at 20% rated output power and 93.48 % efficiency at 100 % of rated output power c) 0.97 power factor at 100% rated output power

ACOUSTICS DATA

A-weighted sound power level (LWA)	52.52 dB(A)

ENERGY CONSUMPTION MEASUREMENT METHODOLOGY

A power meter measured power usage in wattage and amperage in various states (max power, idle mode, and off mode).
For the maximum power measurement, a script was created to run dedicated programs to stress CPU, GPU, memory, storage, etc. in Linux. The manufacturer configured the system to contain maximum power consuming components in each category (CPU, GPU, memory, storage, etc.)

Technical Specifications – Physical Security

PHYSICAL SECURITY AND SERVCEABILITY

Access Panel	Not Tool-less
Storage Drives	Tool-less
Expansion Cards	Tool-less if card mass <1.3 kg
Processor Socket	Soldered
Liquid Cooling Solution	Not field repairable or replaceable
BMC Module	Serviceable. Tools required.
Dual Color Power and HD LED on Front of Computer	Yes
Over-Temp Warning on Screen	Yes
Dual Function Front Power Switch	Yes, causes a fail-safe power off when held for 10 seconds
Cable Lock Support	Kensington Cable Lock (optional): Helps prevent theft of the entire system by securing it to a fixed object. The system includes a standard 3mm x 7mm Kensington lock slot located at the rear.
Setup Password	Yes, prevents an unauthorized person from changing the workstation configuration
NIC LEDs (integrated) (Green & Amber)	Yes

Technical Specifications – Physical Security

Power Supply Diagnostic LED	Yes
Front Power Button	Yes
Front Power LED	Yes, white (normal), red (fault)
Front Hard Drive Activity LED	Yes, white
Internal Speaker	Yes
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.
Cooling Solutions	Closed loop liquid cooling with forced air convection.
Chassis Fan	Six fans, 120x25mm
Access Panel Key Lock	Left and Right access panels can only be secured via a Kensington Lock.
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI). ▪ Allows the system to wake from a low power mode. ▪ Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
PCI Card Retention	Yes, (all), middle (full-height cards), front (cards with extender).
Flash ROM	Yes
Diagnostic Power Switch LED on board	Yes
Clear Password Jumper	Yes
Clear CMOS Button	Yes
CMOS Battery Holder	Yes

Service, Support and Warranty

On-site Warranty[1]: One year (1-1-1), limited warranty and service offering delivers on-site[2], service for parts and labor and includes free telephone support[3] 8am - 5pm. Global coverage[2] ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP waranty.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.
NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries. HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)
- TAA complianT

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uk-en/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpuk-mu_chev/certificates)
- GS Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- CCC Certificates
- Ergonomics

Please contact techregshelp@hp.com

NOTE: The product description/product type/product category for Certifications may be described as any of the following: AI Station/Small Scale Server/Workstation.
Product is TAA Compliant.

Technical Specifications – Environmental

SOCIAL AND ENVIRONMETAL RESPONSIBILITY

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • California Energy Commission (CEC) – Small Scale Servers • Japan Top Runner
Sustainable Impact Specifications	• Product Carbon Footprint
Longevity and Upgrading	This product cannot be upgraded. Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • http://www.epeat.net/Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product is 96.8% recycle-able when properly disposed of at end of life.
Packaging Materials	**External:** PAPER/Corrugated Carton **Internal:** PLASTIC/EPE FOAM/ CUSHION
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Technical Specifications – Environmental

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c05998906):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Technical Specifications – Environmental

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to:
https://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c05403198
or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: HP Product Disassembly Instruction Website. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

- Sustainable Impact Report
  - https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06040843
- Eco-label certifications
  - https://www.hp.com/us-en/sustainable-impact/document-reports.html#filters_documents_reports-=document_type-type_energy_star,type_epeat,type_tcolSO
- ISO 14001 certificates
  - https://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c04777932

Footnotes

1. Recycled plastic is expressed as a percentage of the total weight plastic. Post-consumer recycled is based on the definition set in the EPEAT standard for computers, IEEE 1680.1-2018 standard.
2. Recycled metal is expressed as a percentage of the total weight of the metal according to ISO 14021 definitions for metal parts over 25 grams.
3. HP paper and fiber-based packaging for PCs, displays, home and office print, and supplies is reported by suppliers as recycled or certified, with a minimum of 97% by volume verified by HP. Packaging is the box that comes with the product and all paper-based materials inside the box. Packaging for personal systems accessories and spare parts is not included. Plastic cushions are made from >90% recycled plastic.

MANAGEABILITY

Industry Standard Specifications	This product meets the following industry standard specifications for manageability functionality: ▪ DASH 1.2 (via Intel® LAN on motherboard)
Integrated out-of-band BMC Management	▪ Remote KVM and virtual media ▪ Redfish and IPMI management interfaces ▪ Remote power control and system reset ▪ BIOS and firmware update management ▪ Hardware health monitoring and telemetry ▪ Event logging and diagnostic data collection ▪ Active Directory / LDAP authentication support ▪ SSL certificate management ▪ Configuration backup and restore ▪ Secure firmware and platform management ▪ Dedicated 1GbE management port ▪ Power monitoring and dynamic power management
Intel® vPro® Technology	Yes, when configured with an Intel® vPro™ supporting processor.

Technical Specifications - Storage Drives

STORAGE

HP Z Turbo 2TB PCIe-5x4 2280 SED OPAL2 M.2 SSD	**Capacity**	2TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	500 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 5.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 12000MB/s
	Sequential Write	up to 11000MB/s
	Random Read	up to 1500K IOPS
	Random Write	up to 1300K IOPS
	Self-Encrypting Drive Support	OPAL2

NOTE: Actual performance may vary.

HP Z Turbo 2TB PCIe-5x4 2280 M.2 SSD	**Capacity**	2TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	500 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 5.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 12000MB/s
	Sequential Write	up to 11000MB/s
	Random Read	up to 1500K IOPS
	Random Write	up to 1300K IOPS

Technical Specifications - Storage Drives

HP Z Turbo 4TB PCIe-5x4 2280 M.2 SSD	**Capacity**	4TB
	Protocol	PCIe
	Form Factor	M.2
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	600 TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 5.0 x4 electrical
	Operating Temperature	32° to 158° F (0° to 70° C)
	Performance	
	Sequential Read	up to 12000MB/s
	Sequential Write	up to 11000MB/s
	Random Read	up to 1500K IOPS
	Random Write	up to 1300K IOPS

1. Actual performance may vary.

Technical Specifications – Graphics

GRAPHICS

NVIDIA RTX PRO 2000 Blackwell 16GB	**Form Factor**	Half Height, Half Length (HHHL) 6.6", Double-slot NVIDIA Form Factor 6.0 Compliant
	Graphics Controller	Max Power: 70 Watts Thermal Solution: Active Cooled
	Bus Type	PCI Express 5.0 x 8 Lane and polarity reversal supported
	Memory	16GB GDDR7 with ECC Memory Bandwidth: Up to 288 GB/s Memory Bus width: 128 bits
	Connectors	4x mini DisplayPort 2.1b
	Maximum Resolution	3840 × 2160 × 24 bpp at 480Hz1 7680 × 4320 × 24 bpp at 165Hz1
	GPU Architecture	Blackwell
	Shading Architecture	Shader Model 6.7
	Supported Graphics APIs	DirectX 12 Shader Model 6.7 OpenGL 4.65 Vulkan 1.4
	Available Graphics Drivers	Linux: 570.190 or later Windows: 570 or later

Technical Specifications – Graphics

NVIDIA RTX PRO 4000 Blackwell SFF 24GB	**Form Factor**	Half-height, Half-length (FHFL) 6.6”, dual-slot NVIDIA Form Factor 6.0 compliant
	Graphics Controller	Max Power: 70W Thermal Solution: Active cooled
	Bus Type	PCI Express 5.0 ×8 Lane and polarity reversal supported
	Memory	24 GB GDDR7 with ECC Memory Bandwidth: Up to 432 GB/s Memory Width: 192 bits
	Connectors	4x DisplayPort 2.1b
	Maximum Resolution	4x 3840 x 2160 @ 165 Hz 2x 7680 x 4320 @ 100 Hz
	GPU Architecture	NVIDIA Blackwell
	Shading Architecture	Shader Model 6.6
	Supported Graphics APIs	DirectX 12 Shader Model 6.6 OpenGL 4.63 Vulkan 1.3
	Available Graphics Drivers	Linux: 570.169 or later Windows: 570 or later

Technical Specifications – Graphics

NVIDIA RTX PRO 6000 Blackwell Max-Q 96GB (300W)	**Form Factor**	Full-height, full-length (FHFL) 10.5", dual-slot NVIDIA Form Factor 6.0 compliant
	Graphics Controller	Max Power: 300W Thermal Solution: Active cooled
	Bus Type	PCI Express 5.0 ×16 Lane and polarity reversal supported
	Memory	96 GB GDDR7 with ECC Memory Bandwidth: Up to 1792 GB/s Memory Width: 512 bits
	Connectors	4x DisplayPort 2.1b
	Maximum Resolution	4x 3840 x 2160 @ 165 Hz 2x 7680 x 4320 @ 100 Hz
	GPU Architecture	NVIDIA Blackwell
	Shading Architecture	Shader Model 6.6
	Supported Graphics APIs	DirectX 12 Shader Model 6.6 OpenGL 4.63 Vulkan 1.3
	Available Graphics Drivers	Linux: 570.169 or later Windows: 570 or later

Technical Specifications – Graphics

NVIDIA RTX PRO 6000 Blackwell Workstation Edition 96GB (600W)	**Form Factor**	Extra-height, full-length (XHFL) 12.3", dual-slot NVIDIA Form Factor 6.0 compliant
	Graphics Controller	Max Power: 600W Thermal Solution: Active Cooled
	Bus Type	PCI Express 5.0 ×16 Lane and polarity reversal supported
	Memory	96 GB GDDR7 with ECC Memory Bandwidth: Up to 1792 GB/s Memory Width: 512 bits
	Connectors	4x DisplayPort 2.1b
	Maximum Resolution	4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz
	GPU Architecture	NVIDIA Blackwell
	Shading Architecture	Shader Model 6.6
	Supported Graphics APIs	DirectX 12 Shader Model 6.6 OpenGL 4.63 Vulkan 1.3
	Available Graphics Drivers	Linux: 570.169 or later Windows: 570 or later

Technical Specifications - Weights and Dimensions

WEIGHTS & DIMENSIONS-Packaging

Packaging (WxDxH)	**EPE:** 35.5 x 23.19 x 17.31 in (902 x 589 x 440 mm)
Shipping Weight	**EPE:** 60.82 lb (27.61 kg)
Palletization Profile	2 units per layer 3 layers max 6 units per pallet 1200 x 1000 x 1470 mm (pallet included)

Change Log

SUMMARY OF CHANGES

Date of change	Version History		Description of change
September 25, 2026	From v1 to v2	Addition	Technical Overview and ENERGY DATA sections added
October 19, 2026	From v2 to v3	Correction	Front call outs corrected

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